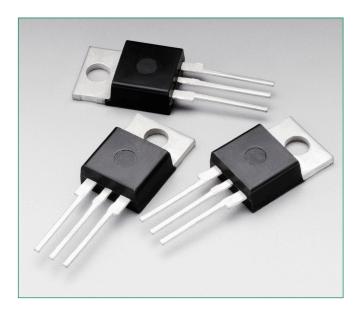


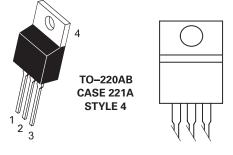
# Surface Mount – 400V - 800V > MAC15 Series

# MAC15M, MAC15N





#### **Pin Out**



## **Description**

Designed for high performance full-wave AC control applications where high noise immunity and high commutating di/dt are required.

## **Features**

- Blocking Voltage to 800 Volts
- On-State Current Rating of 15 Amperes RMS at 80°C
- Uniform Gate Trigger Currents in Three Modes
- High Immunity to dv/dt 250 V/µs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220 Package
- High Commutating di/dt 9.0 A/ms minimum at 125°C
- Operational in Three Quadrants, Q1, Q2, and Q3

## **Functional Diagram**



## **Additional Information**









# **Maximum Ratings** $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (- 40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)  MAC15A6G  MAC15-8G, MAC15A8G	V <sub>drm</sub> , V <sub>rrm</sub>	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 50 to 60 Hz, $T_c = 80$ °C)	I <sub>T (RMS)</sub>	15	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_J = 125^{\circ}\text{C}$ ) Preceded and Followed by Rated Current	I <sub>TSM</sub>	150	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	93	A²sec
Peak Gate Power $(T_C = +80^{\circ}C, \text{ Pulse Width} = 1.0 \mu\text{s})$	$P_{\sf GM}$	20	W
Average Gate Power (t = $8.3 \text{ ms}$ , $T_{c} = 80^{\circ}\text{C}$ )	P <sub>G (AV)</sub>	0.5	W
Operating Junction Temperature Range	Т	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>sJC</sub>	2.0 62.5	°C/W
Maximum Lead Temperature for Solda 10 seconds	ering Purposes, 1/8" from case for	TL	260	°C

<sup>1.</sup> V<sub>DBM</sub> and V<sub>RBM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

# **Thyristors**

# **Electrical Characteristics** - **OFF** $(T_j = 25^{\circ}\text{C unless otherwise noted}; Electricals apply in both directions)$

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	$T_J = 25^{\circ}C$	l <sub>DRM</sub> ,	-	-	0.01	μΑ
$(V_D = V_{DRM} = V_{RRM}, Gate Open)$	T <sub>J</sub> = 125°C	I <sub>RRM</sub>	-	-	2.0	mA

## Electrical Characteristics - ON (T<sub>1</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic			Min	Тур	Max	Unit
Peak On-State Voltage (Note 2) (I <sub>TM</sub> = ±21 A Peak)		V <sub>TM</sub>	-	1.2	1.6	V
Gate Trigger Current	MT2(+), G(+)		5.0	13	35	
(Continuous dc)	MT2(+), G(-)	I <sub>GT</sub>	5.0	16	35	mA
$(V_{D} = 12 \text{ V}, \text{ R}_{L} = 100 \Omega)$	MT2(-), G(-)		5.0	18	35	
Gate Trigger Voltage (Continuous dc) ( $V_D = 12 \text{ V}, R_L = 100 \Omega$ )	MT2(+), G(+)		0.5	0.75	1.5	
	MT2(+), G(-)	V <sub>GT</sub>	0.5	0.72	1.5	V
	MT2(-), G(-)		0.5	0.82	1.5	
	MT2(+), G(+)		-	33	50	
Latching Current $(V_D = 24 \text{ V}, I_G = 35 \text{ mA})$	MT2(+), G(-)	V <sub>GD</sub>	_	36	80	V
	MT2(-), G(-)		-	33	50	
Holding Current ( $V_D = 12 V_{dc}$ , Gate Open, Initiating Current = $\pm 200$ mA))		I <sub>H</sub>	_	20	40	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **Dynamic Characteristics**

Characteristic		Min	Тур	Max	Unit
Rate of Change of Commutating Current; See Figure 10. $(V_D = 400 \text{ V}, \text{ I}_{TM} = 6.0 \text{ A}, \text{ Commutating dv/dt} = 24 \text{ V/µs}, $ $C_L = 10 \text{ µF Gate Open, TJ} = 125 ^{\circ}\text{C}, \text{ f} = 250 \text{ Hz}, \text{ No Snubber})$ $L_L = 40 \text{ mH}$	(di/dt)c	9.0	-	-	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rated V_{DRM'}, Exponential Waveform, Gate Open, TJ = 125°C)$		250	-	-	V/µs

<sup>2.</sup> Indicates Pulse Test: Pulse Width  $\leq$  2.0 ms, Duty Cycle  $\leq$  2% .

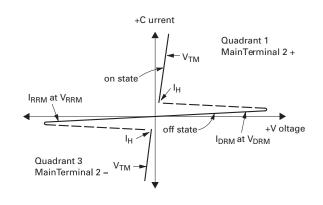


# Surface Mount – 400V - 800V > MAC15 Series

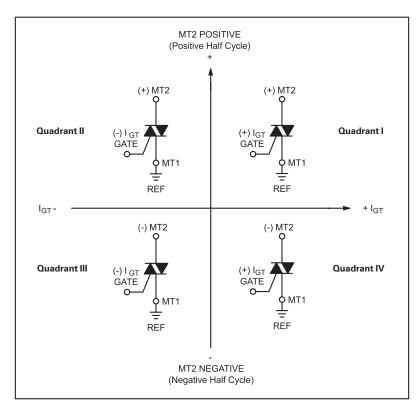
## **Voltage Current Characteristic of SCR**

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current

**Thyristors** 



## **Quadrant Definitions for a Triac**

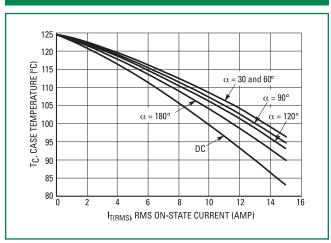


All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.



**Figure 1. RMS Current Derating** 



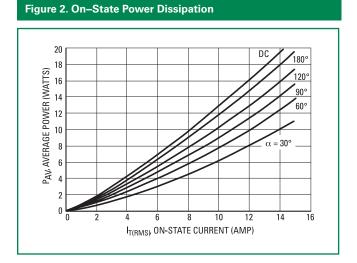


Figure 5. On-State Characteristics

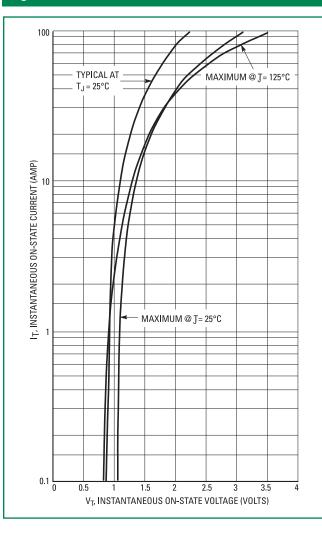


Figure 4. Transient Thermal Response

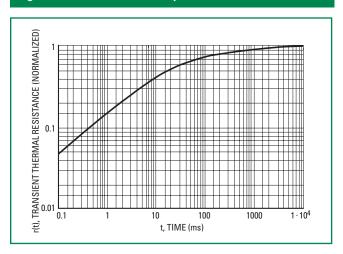


Figure 5. Hold Current Variation

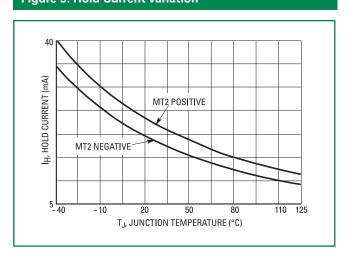




Figure 6. Typical Holding Current vs Junction Temperature

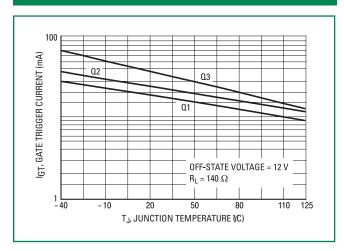


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential)

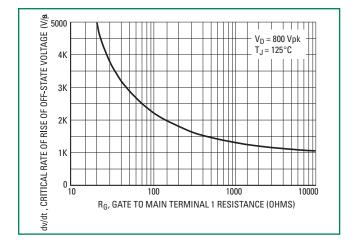


Figure 7. Gate Trigger Voltage vs Junction Temperature

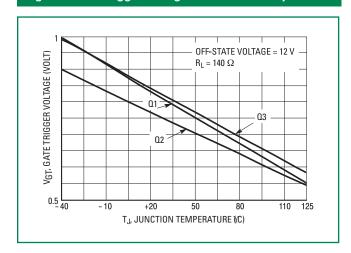


Figure 9. Critical Rate of Rise of Commutating Voltage

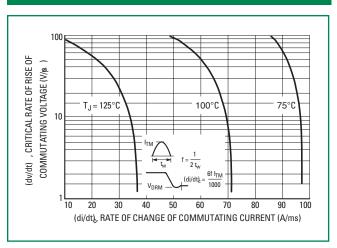
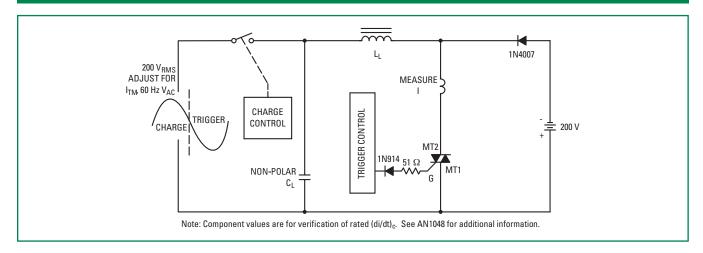
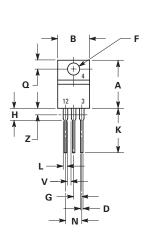
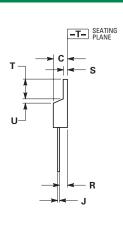


Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)c



#### **Dimensions**

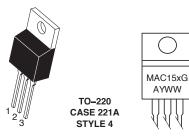




<u> </u>	Inches		Millim	neters	
Dim	Min	Max	Min	Max	
А	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.022	0.36	0.55	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

## **Part Marking System**



 x=
 M or N

 A=
 Assembly Location

 Y=
 Year

 WW
 = Work Week

 G
 = Pb-Free Package

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	Main Terminal 2

## **Ordering Information**

Device	Package	Shipping
MAC15MG	TO-220	50 Units/ Rail
MAC15NG	(Pb-Free)	50 Offics/ Hall

**Disclaimer Notice** - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littlefuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at: <a href="https://www.littlefuse.com/disclaimer-electronics">www.littlefuse.com/disclaimer-electronics</a>